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- State-of-the-Art EPIC-IIB™ BiCMOS Design Significantly Reduces Power Dissipation
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Typical V<sub>OLP</sub> (Output Ground Bounce) < 1 V at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C
- High-Drive Outputs (-32-mA I<sub>OH</sub>, 64-mA I<sub>OL</sub>)
- Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK), Ceramic Flat (W) Package, and Plastic (NT) and Ceramic (JT) DIPs

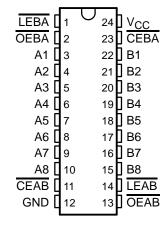
#### description

The 'ABT543A octal transceivers contain two sets of D-type latches for temporary storage of data flowing in either direction. Separate latch-enable (LEAB or LEBA) and output-enable (OEAB or OEBA) inputs are provided for each register to permit independent control in either direction of data flow.

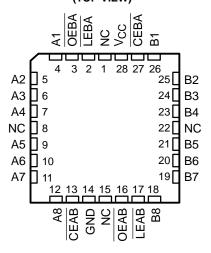
The A-to-B enable  $(\overline{CEAB})$  input must be <u>low to</u> enter data from A or to output data from B. If  $\overline{CEAB}$  is low and  $\overline{LEAB}$  is low, the A-to-B latches are transparent; a subsequent low-to-high transition of  $\overline{LEAB}$  puts the A latches in the storage mode. With  $\overline{CEAB}$  and  $\overline{OEAB}$  both low, the 3-state B outputs are active and reflect the data present at the output of the A latches. Data flow from B to A is <u>similar</u>, but requires using the  $\overline{CEBA}$ ,  $\overline{LEBA}$ , and  $\overline{OEBA}$  inputs.

To ensure the high-impedance state during power up or power down,  $\overline{\text{OE}}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

SN54ABT543A . . . JT OR W PACKAGE SN74ABT543A . . . DB, DW, NT, OR PW PACKAGE (TOP VIEW)



# SN54ABT543A . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

The SN54ABT543A is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT543A is characterized for operation from –40°C to 85°C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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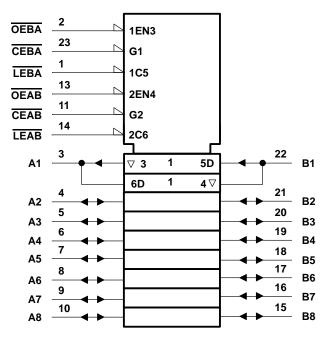
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#### **FUNCTION TABLE**†

	INPU	OUTPUT		
CEAB	LEAB	OEAB	Α	В
Н	Х	Х	Χ	Z
Х	X	Н	Χ	Z
L	Н	L	Χ	в <sub>0</sub> ‡
L	L	L	L	L
L	L	L	Н	Н

<sup>†</sup> A-to-B data flow is shown; B-to-A flow control is the same except that it uses CEBA, LEBA, and OEBA.

# logic symbol§

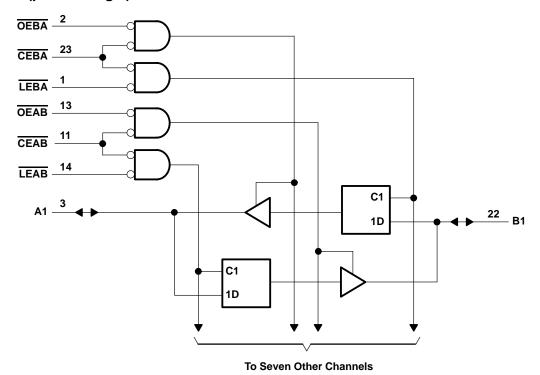


§ This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the DB, DW, JT, NT, PW, and W packages.



<sup>‡</sup>Output level before the indicated steady-state input conditions were established

#### logic diagram (positive logic)



Pin numbers shown are for the DB, DW, JT, NT, PW, and W packages.

### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub>	–0.5 V to 7 V
Input voltage range, V <sub>I</sub> (except I/O ports) (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V <sub>O</sub>	–0.5 V to 5.5 V
Current into any output in the low state, I <sub>O</sub> : SN54ABT543A	96 mA
SN74ABT543A	128 mA
Input clamp current, I <sub>IK</sub> (V <sub>I</sub> < 0)	–18 mA
Output clamp current, $I_{OK}$ ( $V_O < 0$ )	
Package thermal impedance, θ <sub>JA</sub> (see Note 2): DB package	
DW package	
NT package	
PW package	120°C/W
Storage temperature range, T <sub>stg</sub>	

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51, except for through-hole packages, which use a trace length of zero.



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#### recommended operating conditions (see Note 3)

			SN54AB	T543A	SN74AB	T543A	UNIT
			MIN	MAX	MIN	MAX	UNIT
Vcc	Supply voltage		4.5	5.5	4.5	5.5	V
V <sub>IH</sub> High-level input voltage		2		2		V	
VIL	Low-level input voltage			0.8		0.8	V
٧ <sub>I</sub>	V <sub>I</sub> Input voltage		0	VCC	0	VCC	V
ІОН	High-level output current			-24		-32	mA
loL	Low-level output current	eurrent		48		64	mA
Δt/Δν	Input transition rise or fall rate	Outputs enabled		5		5	ns/V
T <sub>A</sub>	Operating free-air temperature		<del>-</del> 55	125	-40	85	°C

NOTE 3: Unused pins (input or I/O) must be held high or low to prevent them from floating.

#### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CO.	NDITIONS	Т	A = 25°C	;	SN54AB	N54ABT543A SN74ABT543A			UNIT	
PAI	RAMETER	I EST CO	SMOITIUMS	MIN	TYP <sup>†</sup>	MAX	MIN	MAX	MIN	MAX	UNII	
VIK		$V_{CC} = 4.5 \text{ V},$	I <sub>I</sub> = -18 mA			-1.2		-1.2		-1.2	V	
		$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -3 \text{ mA}$	2.5			2.5		2.5			
VOН	$V_{CC} = 5 V$ ,	I <sub>OH</sub> = -3 mA	3			3		3		٧		
VOH		V <sub>CC</sub> = 4.5 V	I <sub>OH</sub> = -24 mA	2			2				V	
		vCC = 4.5 v	$I_{OH} = -32 \text{ mA}$	2*					2			
Voi		V00 - 45 V	I <sub>OL</sub> = 48 mA			0.55		0.55			V	
VOL	$V_{OL}$ $V_{CC} = 4.5 V$		I <sub>OL</sub> = 64 mA			0.55*				0.55	V	
V <sub>hys</sub>					100						mV	
ļ.,	Control inputs	V <sub>CC</sub> = 5.5 V,	V22 - F F V	VI = VCC or GND			±1		±1		±1	
l II	A or B ports	ACC = 2.2 A'	Al = ACC of GMD			±100		±100		±100	μΑ	
loz <sub>H</sub> ‡		$V_{CC} = 5.5 \text{ V},$	V <sub>O</sub> = 2.7 V			10§		10§		10§	μΑ	
l <sub>OZL</sub> ‡		$V_{CC} = 5.5 \text{ V},$	V <sub>O</sub> = 0.5 V			-10§		-10§		-10§	μΑ	
l <sub>off</sub>		$V_{CC} = 0$ ,	$V_I$ or $V_O \le 4.5 \text{ V}$			±100				±100	μΑ	
ICEX		V <sub>CC</sub> = 5.5 V, V <sub>O</sub> = 5.5 V	Outputs high			50		50		50	μΑ	
IO¶		V <sub>CC</sub> = 5.5 V,	V <sub>O</sub> = 2.5 V	-50*	-100	-180*	-50	-200	-50	-180	mA	
		V <sub>CC</sub> = 5.5 V,	Outputs high		1	250*		350		250	μΑ	
Icc	A or B ports	$I_{O}=0$ ,	Outputs low		24	30*		34		30	mA	
	V <sub>I</sub> = V <sub>CC</sub> or GNI	$V_I = V_{CC}$ or GND	Outputs disabled		0.5	250*		350		250	μΑ	
ΔI <sub>CC</sub> #		V <sub>CC</sub> = 5.5 V, One ir Other inputs at V <sub>CC</sub>				1.5		1.5		1.5	mA	
Ci	Control inputs	V <sub>I</sub> = 2.5 V or 0.5 V			4						pF	
C <sub>io</sub>	A or B ports	V <sub>O</sub> = 2.5 V or 0.5 V			7						pF	

<sup>\*</sup> On products compliant to MIL-PRF-38535, this parameter does not apply.



<sup>†</sup> All typical values are at V<sub>CC</sub> = 5 V. ‡ The parameters I<sub>OZH</sub> and I<sub>OZL</sub> include the input leakage current.

<sup>§</sup> This data sheet limit may vary among suppliers.

 $<sup>\</sup>P$  Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

 $<sup>^{\#}</sup>$  This is the increase in supply current for each input that is at the specified TTL voltage level rather than V<sub>CC</sub> or GND.

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timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

					SN54AE	3T543A		
				V <sub>CC</sub> :	= 5 V, 25°C	MIN	MAX	UNIT
				MIN	MAX			
t <sub>W</sub>	t <sub>W</sub> Pulse duration, LEAB or LEBA low			3.5		3.5		ns
		Data before LEAB or LEBA↑ L  Data before CEAB or CEBA↑	High	2.5		2.5		ns
1.	Setup time		Low	3		3		
t <sub>su</sub>	Setup time		High	2.5		2.5		115
			Low	3		3	3	
T.,	Hold time	Data after LEAB or LEBA↑	Data after LEAB or LEBA↑			1		nc
th	i ioia time	Data after CEAB or CEBA↑	·	1		1		ns

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

					SN74AE			
	V T				V <sub>CC</sub> = 5 V, T <sub>A</sub> = 25°C		MAX	UNIT
					MAX	1		
t <sub>W</sub> Pulse duration, LEAB or LEBA low			3.5		3.5		ns	
		Data before LEAB or LEBA↑	High	3.5		3.5		
	Setup time		Low	3		3		ns
t <sub>su</sub>	Setup time	Data before CEAB or CEBA↑	High	3.5		3.5		115
		Low		3		3		
t <sub>h</sub> Hold time	Hold time	Data after LEAB or LEBA↑	Data after LEAB or LEBA↑			0.5		ns
	i ioiu uiiie	Data after CEAB or CEBA↑		0.5		0.5		115

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# switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

				SN5	4ABT54	3A		
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>C</sub>	CC = 5 V A = 25°C	', ;	MIN	MAX	UNIT
			MIN	TYP	MAX			
t <sub>PLH</sub>	A or B	B or A	1.6†	4.4	4.4	1.6†	5.5	ns
<sup>t</sup> PHL		BULK	1.6	4.4	5.1	1.6	6.2	115
<sup>t</sup> PLH	LEBA or LEAB	A or B	1.6†	4.1	5.1	1.6†	6.6	ns
<sup>t</sup> PHL		AUD	1.6	4.6	5.4	1.6	6.4	115
<sup>t</sup> PZH	OEBA or OEAB	EBA or OEAB A or B	1.4	3.9	4.1	1.4	5.1	ns
tPZL	OEBA OF OEAB	AUID	2	5	4.9	2	5.8	115
<sup>t</sup> PHZ	OEBA or OEAB	A or B	2.5†	5.9	5.8	2.5†	6.9	ns
<sup>t</sup> PLZ	OEDA OI OEAD	AOID	2.5†	5.5	6.1	2.5†	7.6	115
<sup>t</sup> PZH	CEBA or CEAB	A - :: D	1.4	3.9	4.7	1.4	5.6	ns
tPZL	CEBA OF CEAB	A or B	2	5	5.7	2	6.2	115
<sup>t</sup> PHZ	CEBA or CEAB	A or B	3.2†	5.9	6.5	3.2†	7.3	no
t <sub>PLZ</sub>	CLDA OF CEAD	AUIB	2.5†	5.5	6.7	2.5†	7.8	ns

<sup>†</sup> This data sheet limit may vary among suppliers.

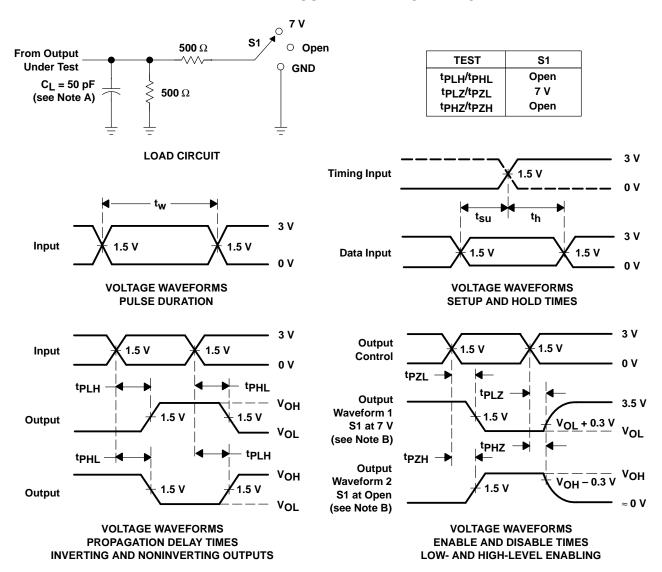
# switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L$ = 50 pF (unless otherwise noted) (see Figure 1)

				SN7	4ABT54	3A			
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub> = 5 V, T <sub>A</sub> = 25°C		MIN	MAX	UNIT		
			MIN	TYP	MAX				
<sup>t</sup> PLH	A or B	B or A	1.8†	4.4	5.9	1.8†	6.9	ns	
<sup>t</sup> PHL		BULK	1.9	4.4	5.9	1.9	6.9	115	
tPLH	LEBA or LEAB	A or B	1.5†	4.1	5.6	1.5†	6.6	ns	
t <sub>PHL</sub>		AUD	2.1	4.6	6.1	2.1	7.1	115	
<sup>t</sup> PZH	OEBA or OEAB	A or B	1.4	3.9	5.4	1.4	6.4	ns	
t <sub>PZL</sub>	OEBA OI OEAB	AOID	2.5	5	6.5	2.5	7.5	115	
<sup>t</sup> PHZ	OEBA or OEAB	or OEAB A or B	2.5†	5.9	7.4	2.5†	8.4	ns	
t <sub>PLZ</sub>	OEBA OI OEAB	AOID	2.5†	5.5	7	2.5†	8	115	
<sup>t</sup> PZH	CEDA or CEAD	CEBA or CEAB A or B	1.4	3.9	5.4	1.4	6.4	ns	
t <sub>PZL</sub>	CEBA OF CEAB		2.5	5	6.5	2.5	7.5	115	
<sup>t</sup> PHZ	CEBA or CEAB	A or B	2.9†	5.9	7.4	2.9†	8.4		
<sup>t</sup> PLZ	OLDA OI OLAB	AUID	2.4†	5.5	7	2.4†	8	ns	

<sup>†</sup>This data sheet limit may vary among suppliers.



#### PARAMETER MEASUREMENT INFORMATION



NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_{O} = 50 \Omega$ ,  $t_{f} \leq$  2.5 ns,  $t_{f} \leq$  2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

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